CODE: FD8 REV B DATE: 8/31/2018

SOLDERABLE TERMINATION FINISHES (NO PURE TIN)

1.0 Definition of terms:

1.01 The term "shall", "will" and "may" are used with specific intent thought-out these documents and will observe the following rules:

1.1 Requirements defined using "**shall**" in the text are mandatory requirements and are considered to be binding and require formal verification. Departure from such a requirement is not permissible without formal agreement between Subcontractor and CSPI.

1.2 Requirements defined using "**will**" in the text expresses a provision or service by CSPI or an intention by CSPI in connection with a requirement of this document. The subcontractor is implicitly authorized to rely on such service or intention.

1.3 The word "**may**" in the text expresses a permissible practice or action. It does not express a requirement of this document.

2.0 Solderable Termination Finishes (No Pure Tin)

2.0.1 Components and components in completed subassemblies furnished under this Purchase Orders shall not be received with any of the termination finishes listed below. The termination finish shall meet the solderability requirements of ANSI/J-STD-002 or EIA JESD22-B102 as a minimum and must accept solder at 200 degrees Celsius or less. ANSIIJ-STD-002 is the preferred test method. A double tinning or dynamic solder wave process shall be used for any gold plating removal.
See also GEIA-STD-0005-1 and GEIA-STD-0005-2 standards.

3.0 Non-Approved Termination Finishes:

3.0.1 Any solder containing tin (SN) that does not contain at least 3% lead (Pb).

3.0.2 This includes, but not limited to:

3.0.2.a Pure tin (Sn) .

3.0.2.b Tin-Bismuth (SnBi) .

3.0.2.c Tin-Silver-Copper (SnAgCu or SAC) .

3.0.2.d Tin-Silver (SnAg)